	Туре	L#	Hits	Search Text	DBs	Time Stamp	C o m m e nt s	in rs iti
1	BRS	L1	1072	(etch\$3 or immers\$3) same "solder bumps"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:27	:	0
2	BRS	L8	339	1 and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 11: <b>4</b> 6		0
3	BRS	L15	132	8 and @pd<=20000531	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 11: <b>4</b> 7		0
4	BRS	L22	2623317	(etch\$3 or immers\$3) same "solder bumps"same rotat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:30		0
5	BRS	L29	1	(etch\$3 or immers\$3) with "solder bumps" with rotat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:31		0